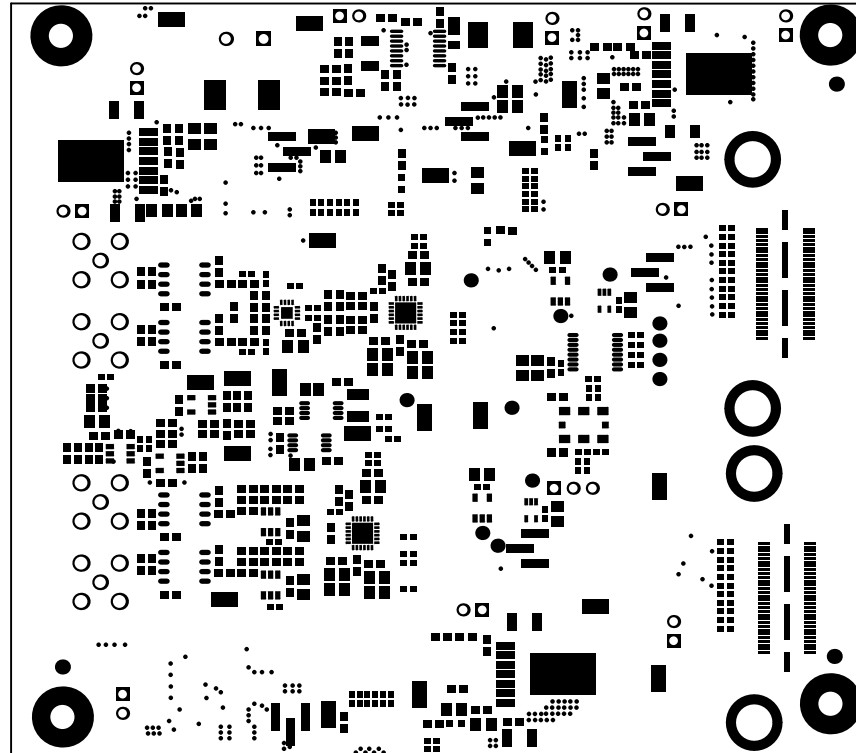
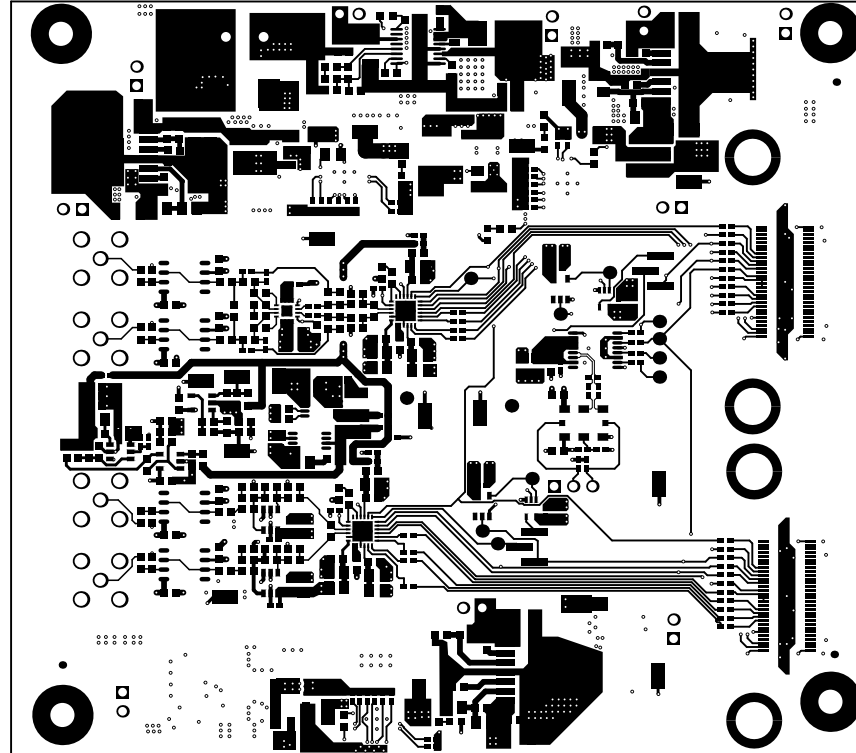


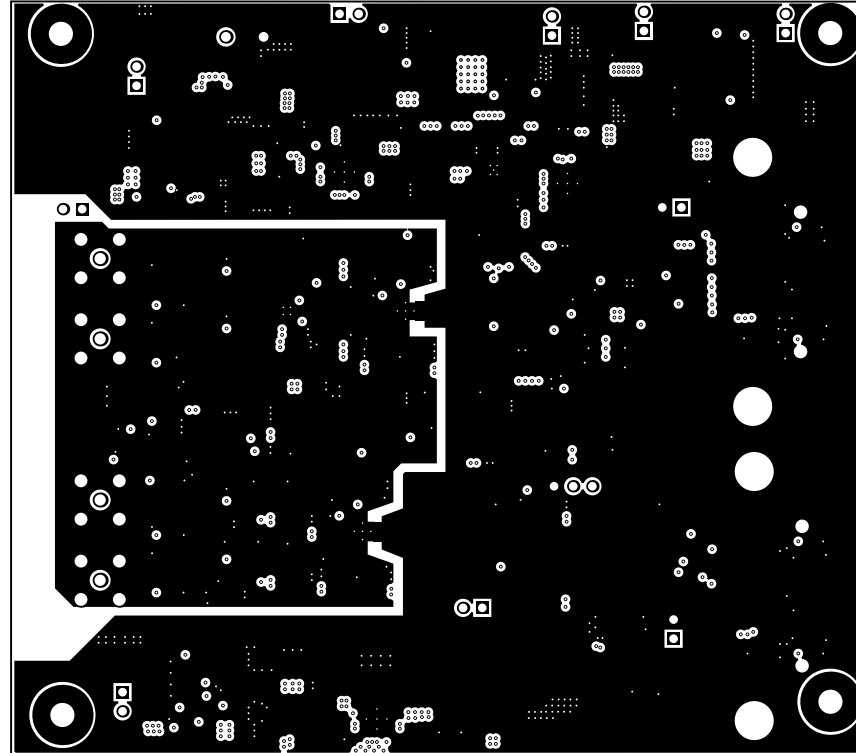
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01057		
PLOT NAME = Top Overlay	GENERATED : 2017/12/14 17:55:40		TEXAS INSTRUMENTS



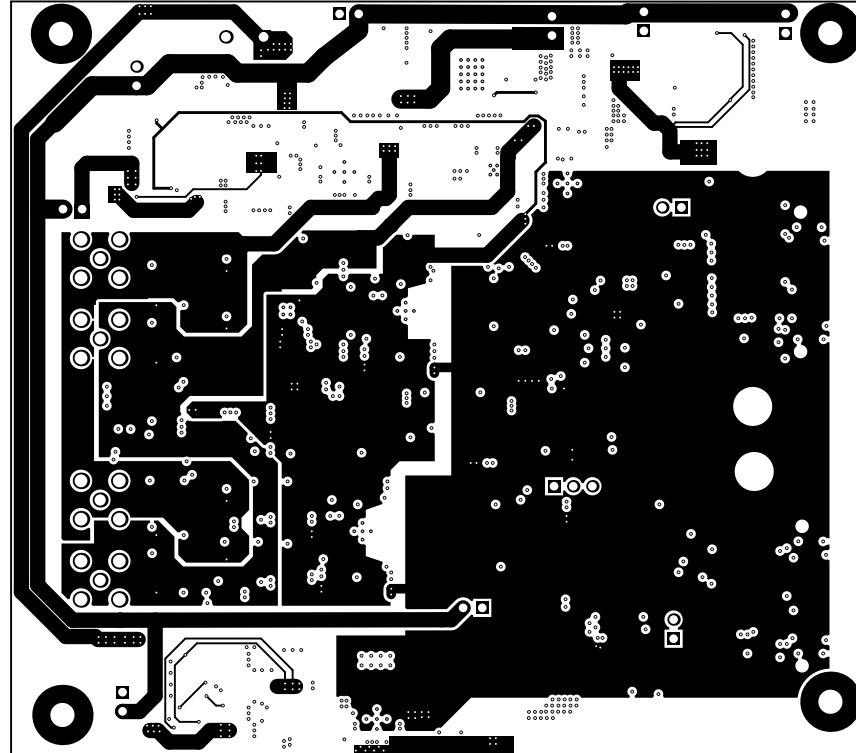
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01057		
PLOT NAME = Top Solder Mask	GENERATED : 2017/12/14 17:55:41	TEXAS INSTRUMENTS	



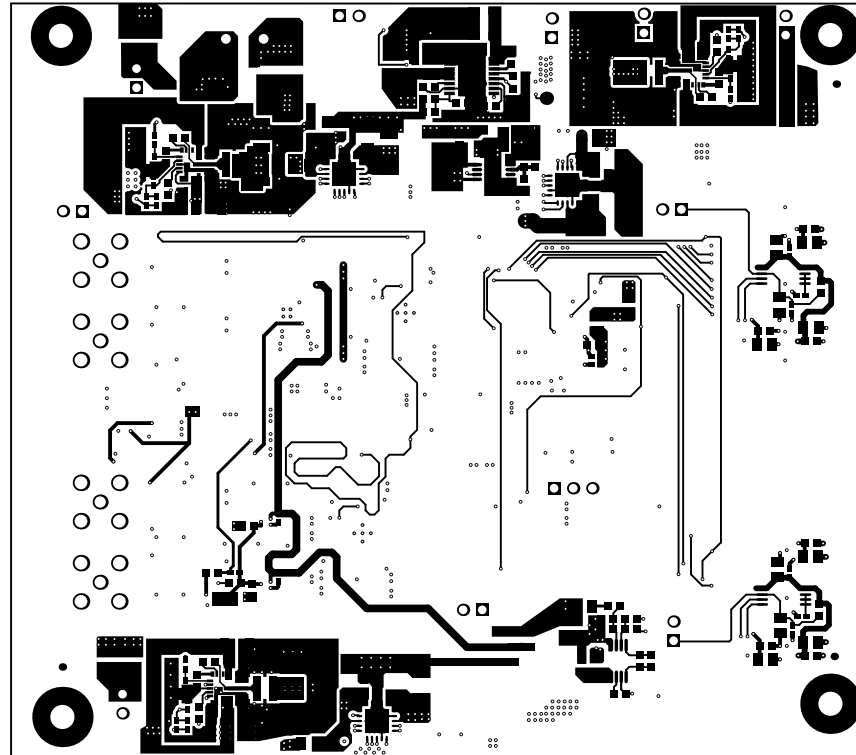
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: 01057		
PLOT NAME = Top Layer	GENERATED : 2017/12/14 17:55:42	TEXAS INSTRUMENTS	



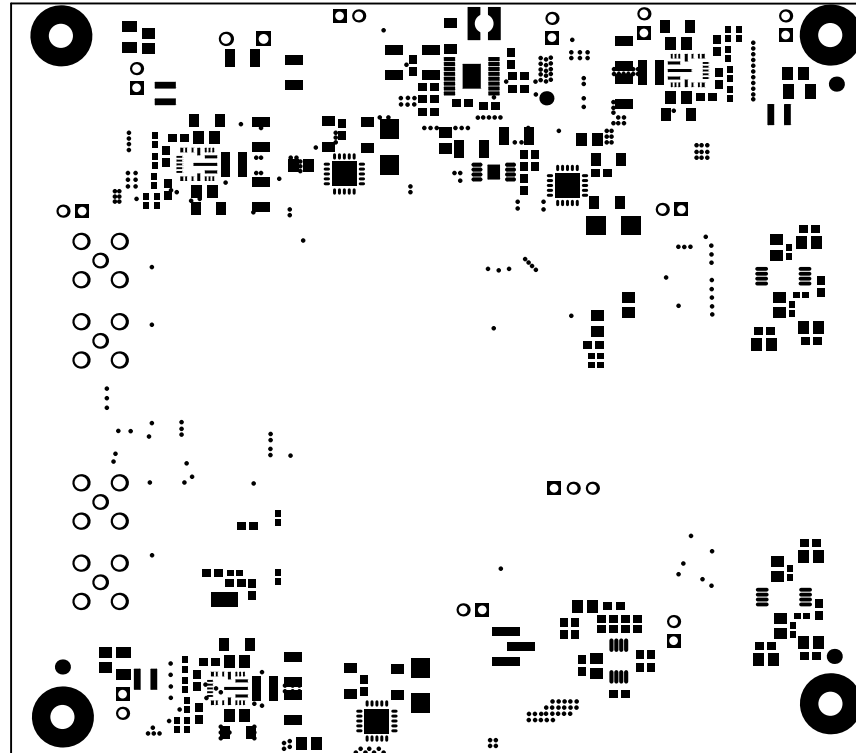
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND	TID #: 01057		
PLOT NAME = Signal Layer 1	GENERATED : 2017/12/14 17:55:43	TEXAS INSTRUMENTS	



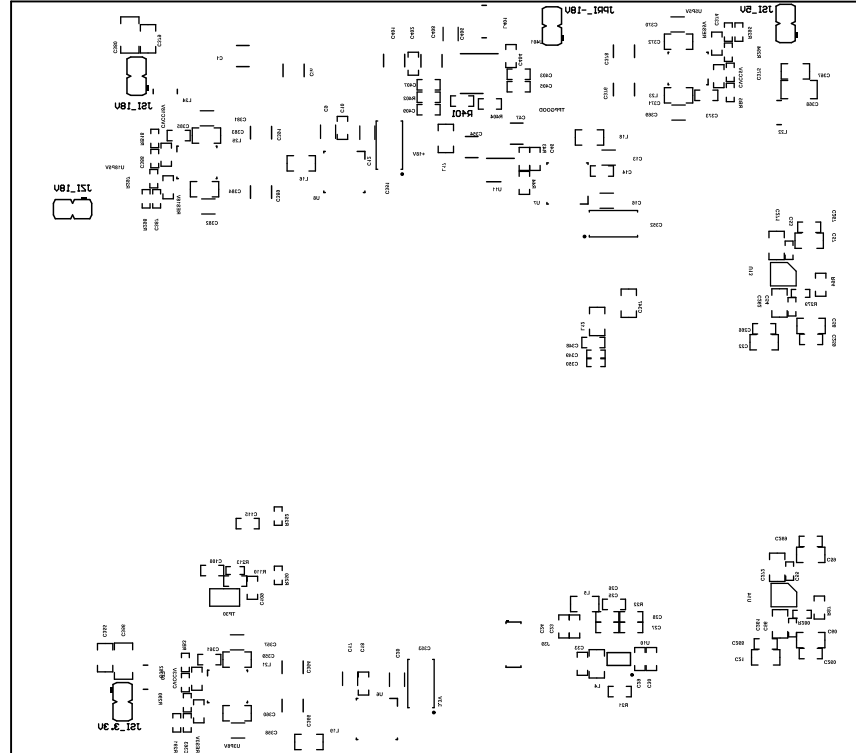
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - PWR	TID #: 01057		
PLOT NAME = Signal Layer 2	GENERATED : 2017/12/14 17:55:44	TEXAS INSTRUMENTS	



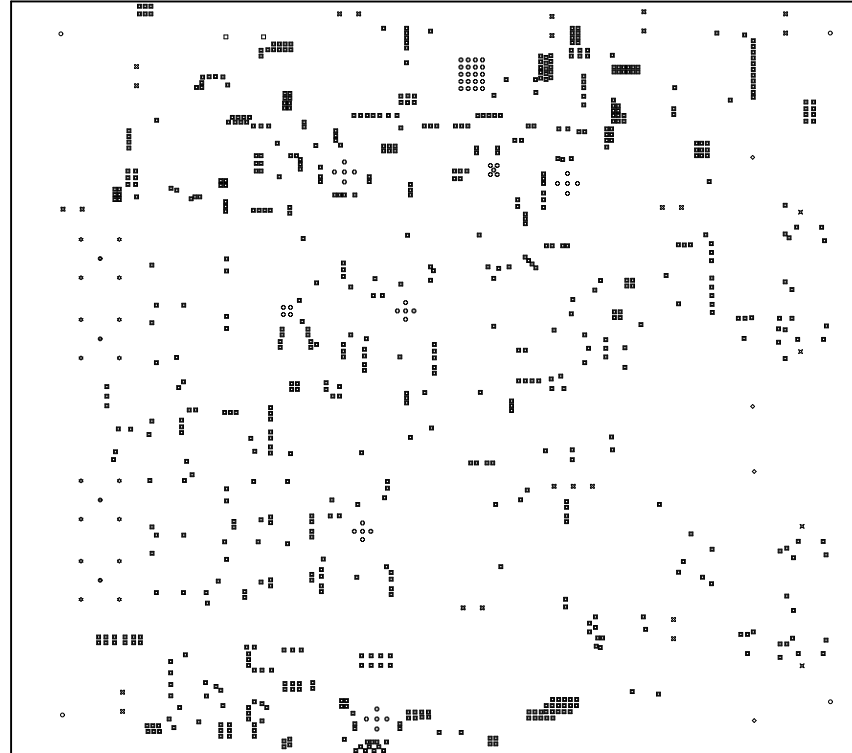
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: 01057		
PLOT NAME = Bottom Layer	GENERATED : 2017/12/14 17:55:45	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01057		
PLOT NAME = Bottom Solder Mask	GENERATED : 2017/12/14 17:55:46	TEXAS INSTRUMENTS	

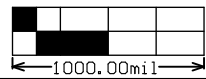
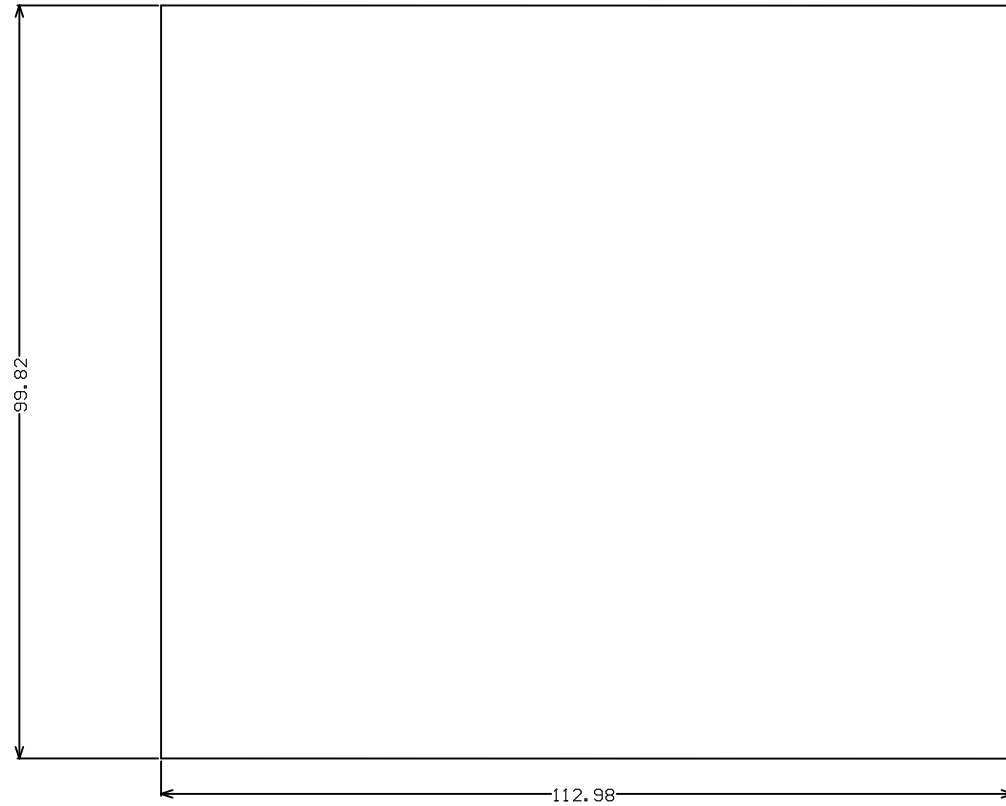


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01057		
PLOT NAME = Bottom Overlay	GENERATED : 2017/12/14 17:55:47	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	4	40,00mil (1,016mm)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
◇	4	173,23mil (4,400mm)	NPTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊙	54	7,87mil (0,200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
■	716	10,00mil (0,254mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊗	23	45,28mil (1,150mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
□	2	51,18mil (1,300mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
●	4	59,06mil (1,500mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊛	16	66,93mil (1,700mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
○	4	125,98mil (3,200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
	827 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01057		
PLOT NAME = Drill Drawing	GENERATED : 2017/12/14 17:55:48	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01057	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01057		
PLOT NAME = Board Dimensions	GENERATED : 2017/12/14 17:55:51	TEXAS INSTRUMENTS	

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